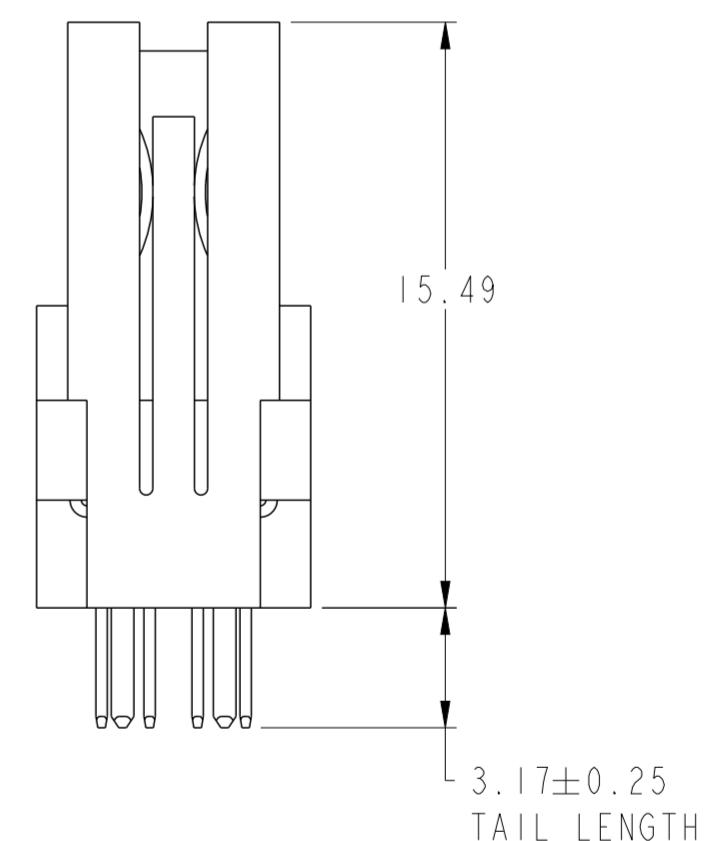
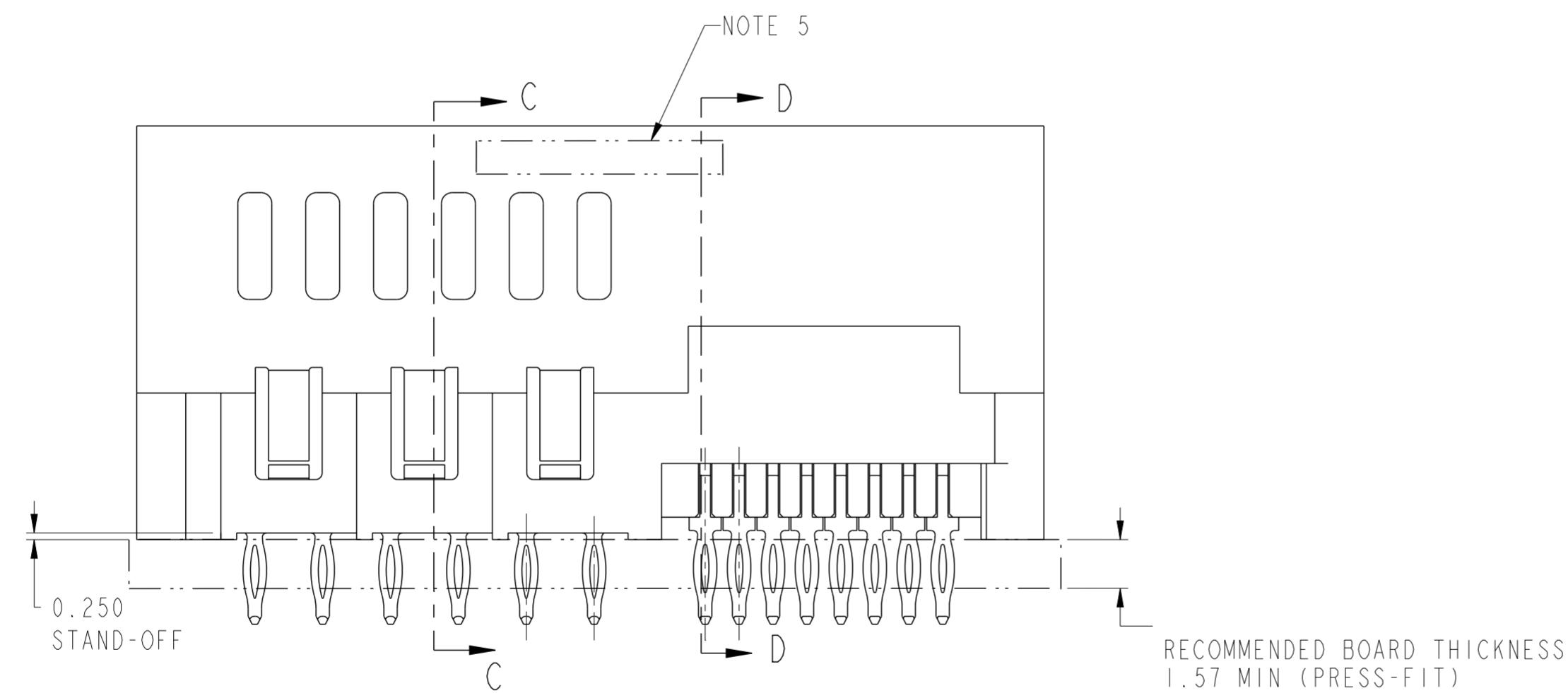
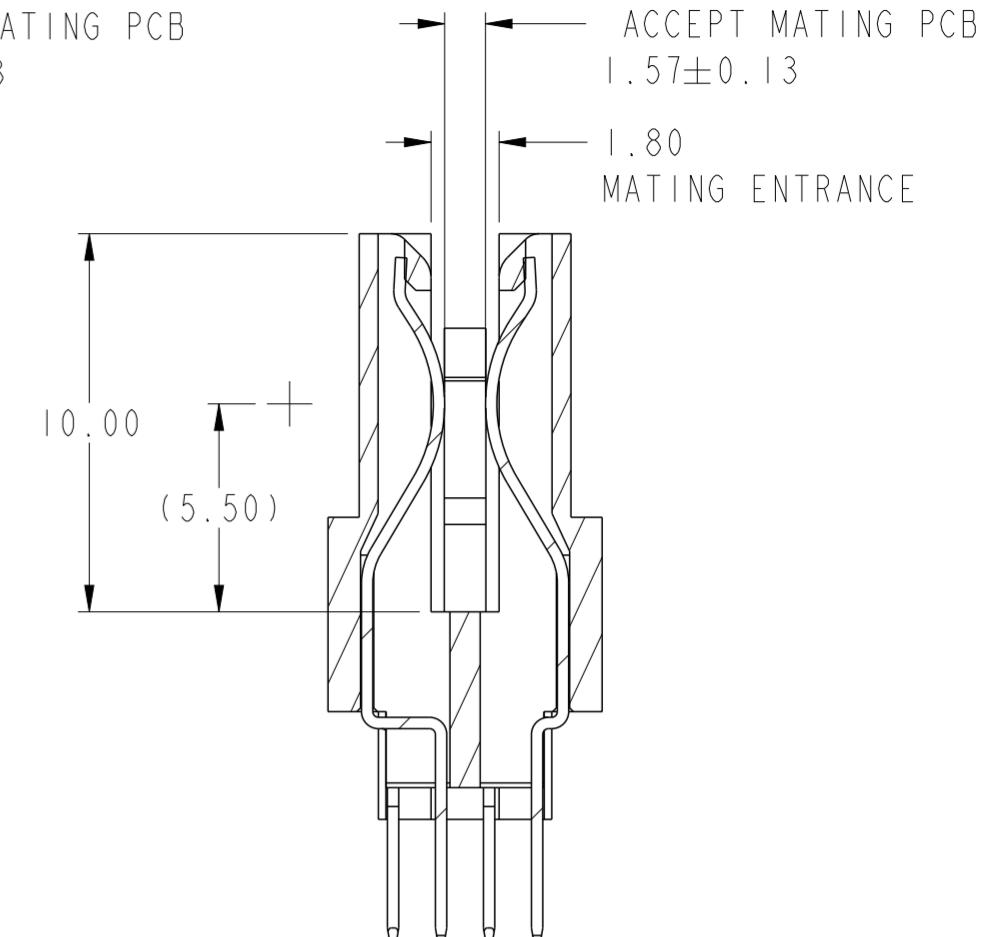
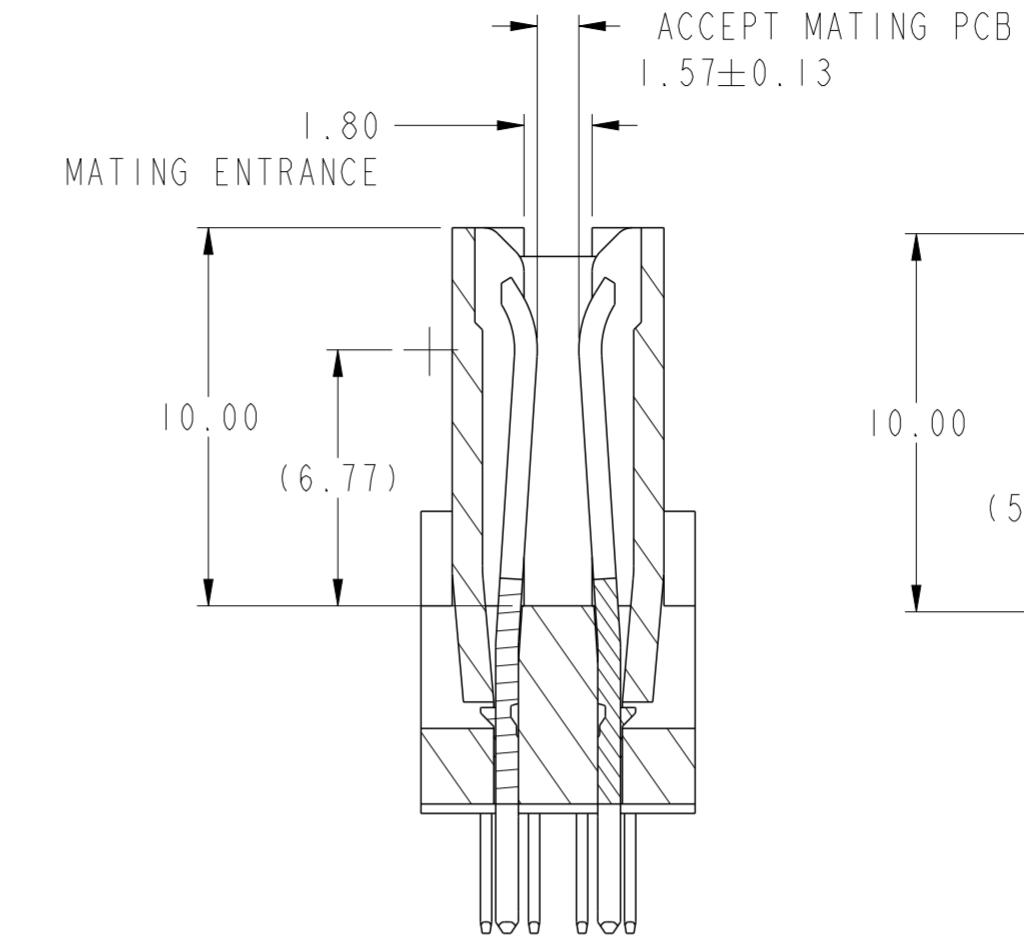
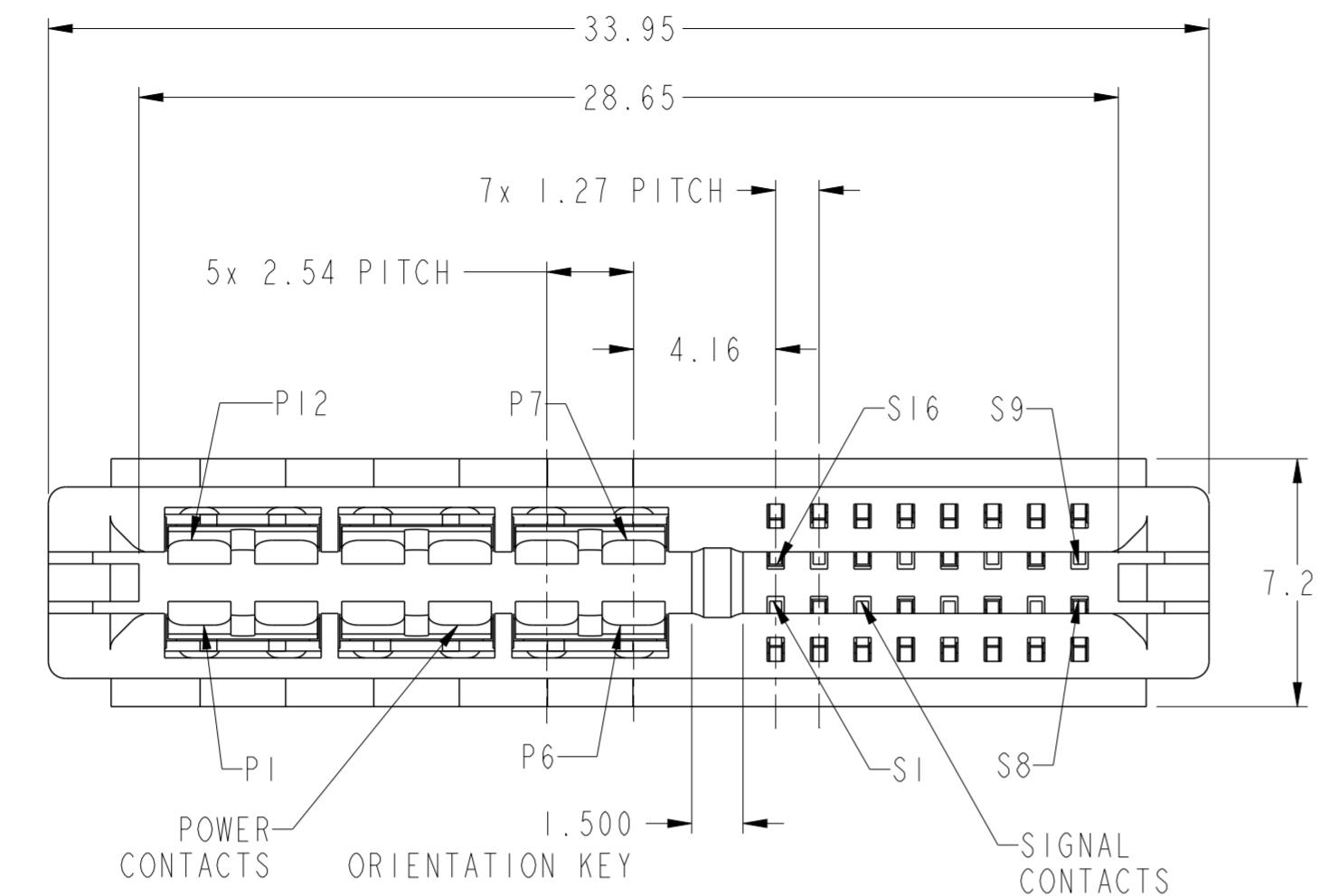
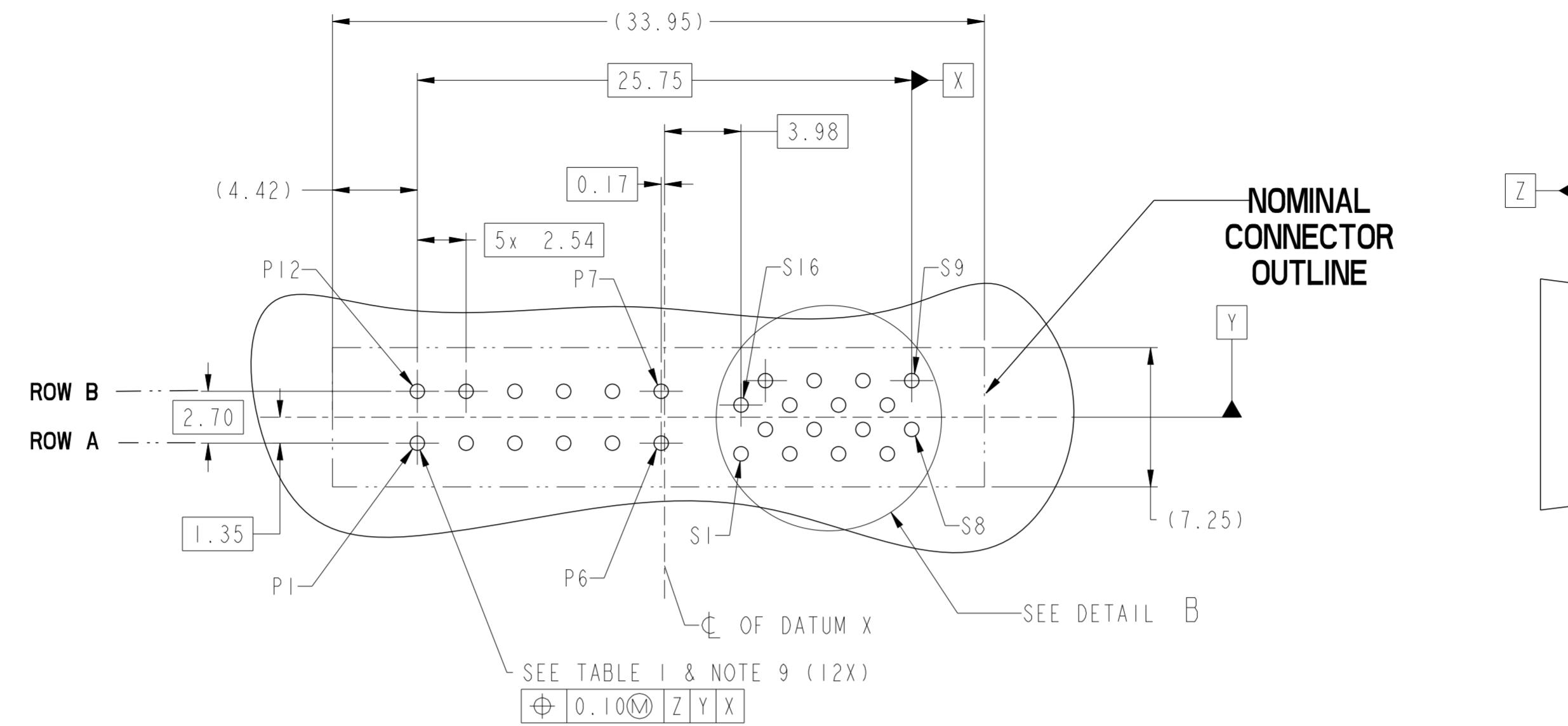


PART NUMBER | 10125705-001LF

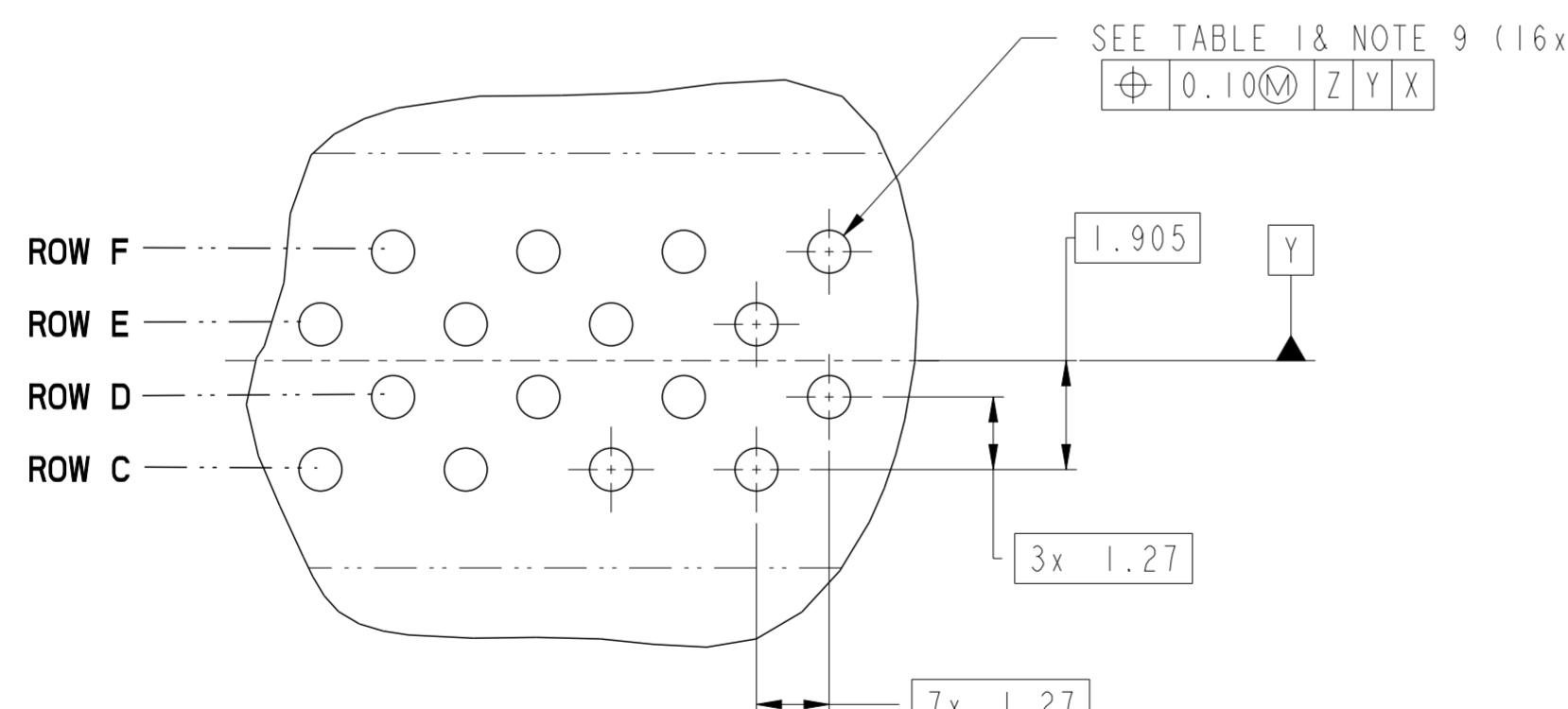
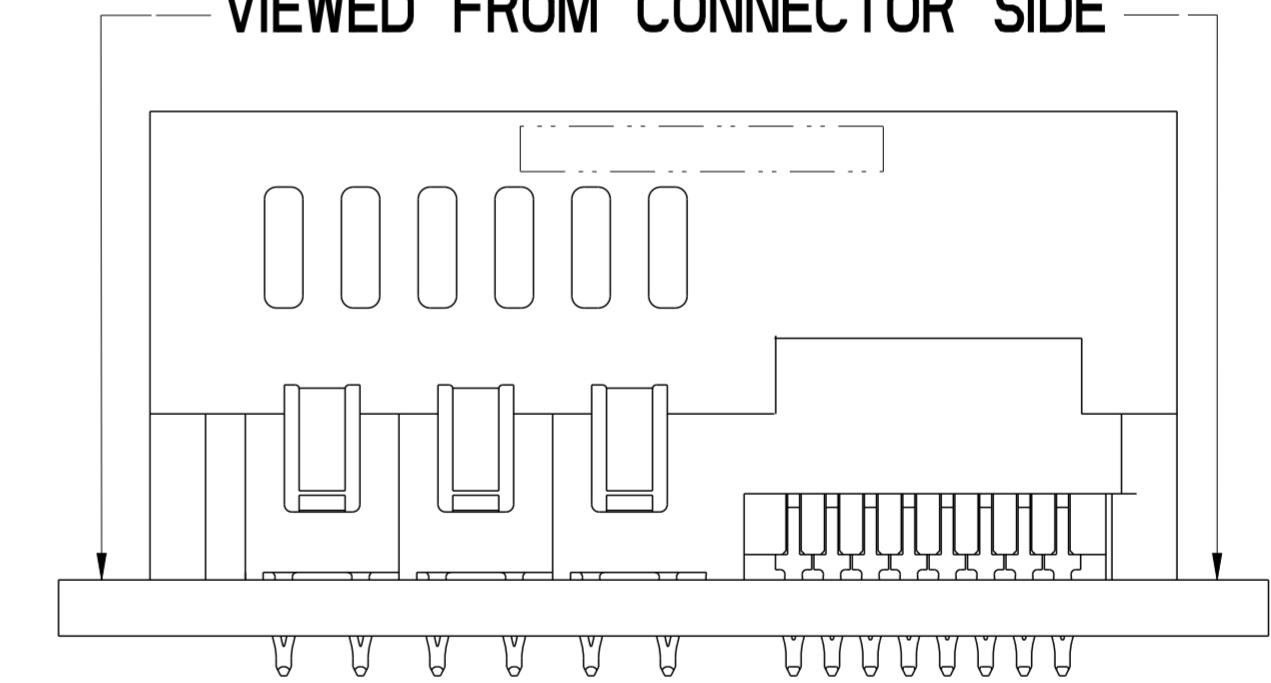


spec ref	-	dr	Jackie Huang	2014/10/31	projection 	mm	size	A2	scale	5:1		
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED ISO 406 ISO 1101	eng	Sunny2 Liu	2016/04/12			ecn no	ELX-DG-22934-1				
chr		terriss Liu	2016/05/20	rel level			Released					
appr		Pei-Ming Zheng	2016/05/24	product family			CARD EDGE					
surface	linear	0.X	± 0.5	Amphenol FCi				10125705				
		0.XX	± 0.25	VERT RECP (12P 16S)				dwg B				
		0.XXX	± 0.10	MEZZANINE HPCE								
ASME Y14.5	angular	0°	$\pm 2°$	cat. no.	-	Product	Customer	Drw	sheet 1 of 3			

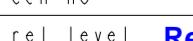
NOMINAL CONNECTOR OUTLINE



RECOMMENDED PCB LAYOUT VIEWED FROM CONNECTOR SIDE



DETAIL
SCALE 8

spec ref	-		dr	Jackie Huang		2014/10/31			size	A2	scale	2:1	
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED		eng	Sunny2 Liu		2016/04/12			ecn no	ELX-DG-22934-1			
ISO 406			chr	Terris Liu		2016/05/20			rel level	Released			
ISO 1101			appr	Pei-Ming Zheng		2016/05/24			product family				
surface			linear	0.X	± 0.5								
				0.XX	± 0.25								
				0.XXX	± 0.10								
ASME Y14.5	angular			0°	$\pm 2°$		cat. no.	-	Product - Customer Drw		sheet 2 of 3		

CONTACT TYPE	TOP LAYER DESCRIPTION	TABLE I (HPCE / PRESS-FIT TAILS) PLATED THROUGH-HOLE REQUIREMENTS				
		DRILLED HOLE DIAMETER	COPPER THICKNESS	TIN-LEAD THICKNESS	TIN THICKNESS	FINISHED HOLE DIAMETER
POWER & SIGNAL	TIN-LEAD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	0.005 - 0.015	--	0.65 - 0.80
	IMMERSION TIN	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	0.9 - 1.5um	0.70 - 0.80
	COPPER (SEE NOTE 8)	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	0.70 - 0.80

NOTES:

I. CONNECTOR MATERIALS:

HOUSING: HIGH TEMPERATURE THERMAL PLASTIC, BLACK
UL 94V-0 COMPLIANT

CONTACTS: HIGH PERFORMANCE COPPER ALLOY.

2. CONTACT FINISH REF. GS-12-604 SECTION 5.2.

3. PRODUCT SPECIFICATION: GS-12-1261.

4. APPLICATION SPECIFICATION: GS-20-128.

5. PRODUCT MARKING ON HOUSING IN AREA SHOWN MEETS AFCI SPECIFICATION: GS-24-007.

6. PACKAGING MEETS FCI SPECIFICATION GS-14-937.

7. HOUSING COMPONENT WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE
FOR 60 SECONDS IN A CONVECTION, INFRA-RED, OR VAPOR PHASE REFLOW OVEN.

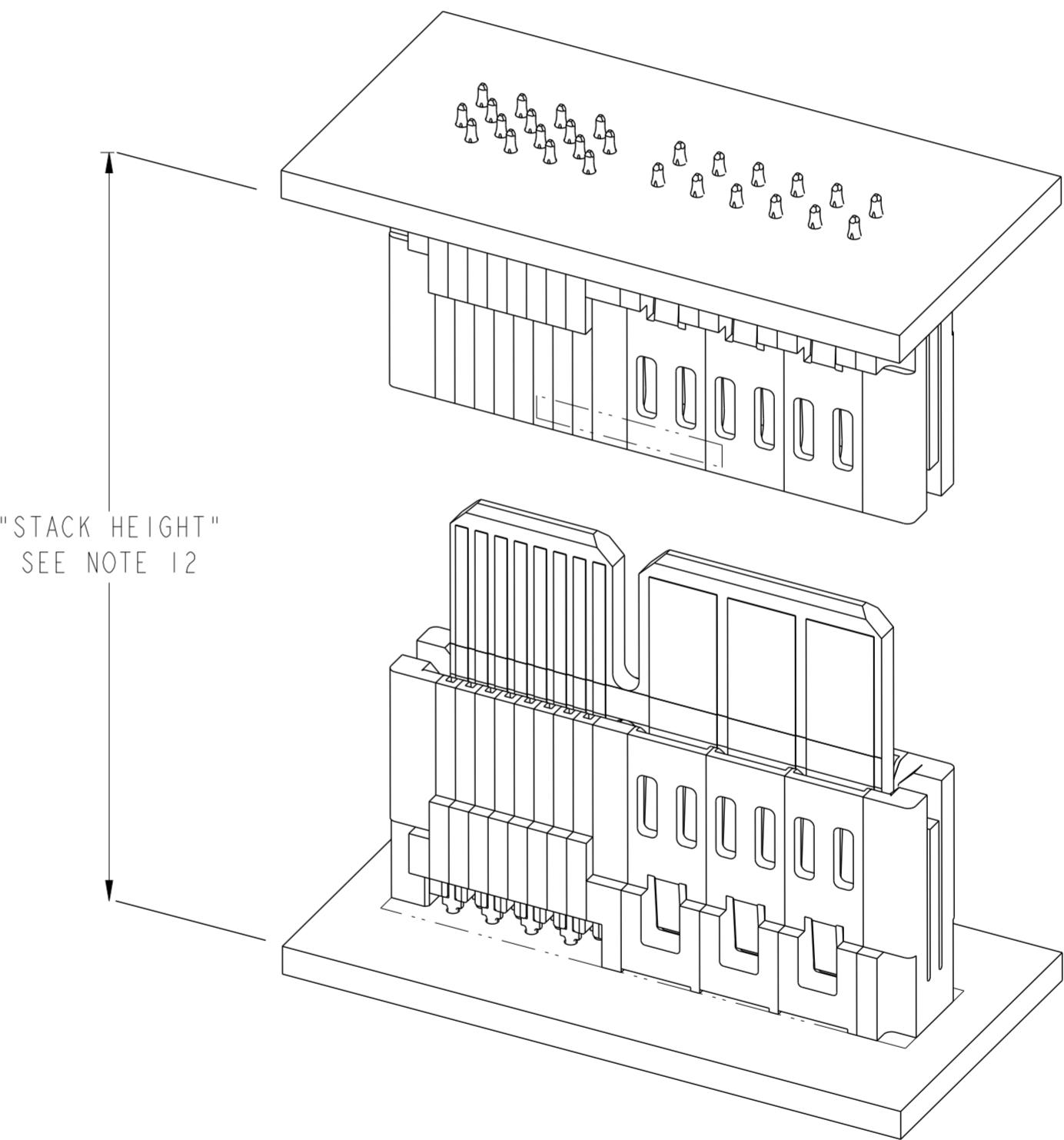
8. COPPER PLATING THICKNESS IN CENTER OF VIA-HOLE CAN BE NO MORE THAN 0.003 LESS THAN OTHER AREAS

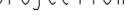
9. ALL HOLE SIZES ARE FINISHED HOLE SIZES.

10. INTENDED USE: TWO ASSEMBLIES (P/N 10122776) MEZZANINE STACKED USING PCB TO CONTROL STACK HEIGHT
DIM "L" + 10.98mm = FINAL MEZZANINE STACK HEIGHT.
DIM "L" RANGES FROM 21.02-31.02 mm IN 1 mm INCREMENTS.

11. SEE DRAWING 10125707 FOR MATING PCB DETAIL

12. A SYMBOL  WILL BE NEXT TO ANY DIMENSION, VIEW, OR NOTE WHICH HAS BEEN
MODIFIED WITH THE CURRENT DRAWING REVISION.



spec ref	-	dr	Jackie Huang	2014/10/31	projection 	mm	size	A2	scale	1 : 1		
tolerance std	TOLERANCES UNLESS OTHERWISE SPECIFIED	eng	Sunny2 Liu	2016/04/12			ecn no	ELX-DG-22934-1				
ISO 406 ISO 1101		chr	Terris Liu	2016/05/20			rel level	Released				
	appr	Pei-Ming Zheng	2016/05/24	product family								
surface	linear	0.X	±0.5	Amphenol FCI				dwg	10125705	rev B		
		0.XX	±0.25									
		0.XXX	±0.10	VERT RECP (12P 16S) MEZZANINE HPCE								
ASME Y14.5	angular	0°	±2°	cat. no. - Product - Customer Drw				sheet 3 of 3				